What is Claimed:

1. A process for manufacturing a transaction card comprising the steps of:

(a) forming an opening in a card body of the transaction card;

(b) molding a molding material about an electronic component; and

(c) inserting and securing the electronic component into the opening in the card body wherein the electronic component comprises an antenna configured to couple to a payment module.

2. The process of claim 1, wherein the antenna comprises a planar, metal, annular member having an antenna discontinuity that connects an inner region defined by the annular member to an outer region that surrounds the annular member.

3. The process of claim 2, wherein the molding step disposes molding material in the antenna discontinuity, the inner region, and the outer region,

4. The process of claim 1, wherein the molding step comprises inserting the electronic component into the opening and then filling the opening with the molding material.

5. The process of claim 1, wherein the molding step comprises placing the electronic component into a mold and injecting the molding material into the mold, and then inserting and securing the molded electronic component into the opening in the card body.

6. The process of any one of claims 1 -5, wherein step (a) comprises forming one or more securing features in the card body.

7. The process of claim 6, wherein the one or more securing features comprise at least a first securing feature as a blind hole pocket open only to a first face of the card body and at least a second securing feature as a blind hole pocket open only to a second face of the card body.

8. The process of any one of claims 1-7, wherein the opening extends entirely through the card body.

9. The process of any one of claims 1-7, wherein the opening extends only partially through the card body.

10. The process of any one of claims 1-9, wherein the molding material is one or more of EVA, metallocene polyalphaolefins, polyolefins including atactic polyalphaolefins, block copolymers, polyurethane hot melts, polyamides, fiberglass reinforced polyester, polyurethane, bakelite, duroplast, melamine, Diallyl-phthalate, and polyimide.

11. The process of any one of claims 1-9, wherein the molding material is a plastic having a molding temperature range of approximately 150-300 °C.

12. The process of any one of claims 1-11, further comprising, after the molding step, the step of removing excess molding material from the molded electronic component.

13. The process of claim 3, further comprising, after the antenna is disposed in the card body, creating an opening in the molding material of the inner region defined by the annular member, and securing the payment module in the opening.

14. The process of claim 13, further comprising creating at least one body discontinuity from an outer periphery of the card body to the opening in the card body.

15. The process of claim 14, wherein the at least one body discontinuity extends parallel to the outer periphery of the card body.

16. The process of claim 14, wherein creating the at least one body discontinuity comprises creating at least two body discontinuities, wherein the at least two body discontinuities and the opening collectively bisect the card body into at least two discrete portions.

17. The process of claim 16, wherein creating the at least one body discontinuity comprises creating at least two body discontinuities, wherein one of the at least two body discontinuities extends in a first path and another of the at lest two body discontinuities extends in a second path.

18. The process of claim 17, wherein the first path and the second path extend along one side of the antenna.

19. The process of claim 17, wherein the first path extends along one side of the antenna and the second path extends along an opposite side of the antenna.

20. The process of any one of claims 17-19, wherein the first path is parallel relative to the second path.

21. The process of any one of claims 17-19, wherein the first path is non-parallel relative to the second path.

22. The process of any one of claims 14-21, wherein the at least one body discontinuity has non-linear geometry.

23. The process of any one of claims 1-9 and 13-22, wherein the molding material comprises a resin including powdered metal.

24. The process of claim 23, wherein the powdered metal is selected from the group consisting of Rhodium, Aluminum, Titanium, Magnesium, Copper, Brass, Nickel, Monel, Inconel, Steel, alloys of the foregoing, and combinations of the foregoing.

25. The process of claim 24, wherein the card body comprises a metal, further comprising selecting the powdered metal included in the resin to provide for a color and tone of the molding material to match a color and tone of the metal card body.

26. The process of claim 25, wherein the powdered metal included in the resin and the metal of the card body comprise the same type of metal or alloy thereof.

27. The process of any one of claims 1-26, wherein the card body has different materials of construction than the molding material, further comprising tailoring a coloration of the molding material to match a coloration of the body.